

Listing of Claims

1. (Currently Amended) A laminated component for use in manufacturing articles such as printed circuit boards, said component comprising:
 - a conductive film layer; and
 - a non-functional film layer joined to a first surface of said conductive film layer, wherein one of said conductive film layer and said non-functional film layer has larger lateral dimensions than the other of said conductive film layer and said non-functional film layer such that a portion of said one film layer extends beyond said other film layer.
2. (Original) The component of claim 1 wherein said conductive film layer and said non-functional film layer are joined together by adhesive.
3. (Original) The component of claim 1 wherein said conductive film layer and said non-functional film layer are joined together by a band of adhesive defining a sealed central area inwardly thereof.
4. (Original) The component of claim 1 wherein said portion of said one film layer extends beyond said other film layer on all sides thereof.
5. (Original) The component of claim 1 wherein said one film layer and said other film layer are joined together at the periphery of said other film layer.
6. (Original) The component of claim 1 wherein said conductive film layer is made of copper.
7. (Original) The component of claim 1 wherein said non-functional film layer is made of a material selected from the group consisting of aluminum, polytetrafluoroethylene, silicone, paper-based material, and cotton-based material.
8. (Currently Amended) A laminated component for use in manufacturing articles such as printed circuit boards, said component comprising:
 - a first film layer;
 - a second film layer disposed against said first film layer, said second film layer having larger lateral dimensions than said first film layer such that a portion of said second film layer extends beyond said first film layer, wherein one of said first and second film layers is made of an electrically conductive material; and

a band of adhesive joining said first and second film layers and defining a sealed central area inwardly thereof.

9. (Original) The component of claim 8 wherein said second film layer extends beyond said first film layer on all sides thereof.

10. (Original) The component of claim 8 wherein said first film layer and said second film layer are joined together at the periphery of said first film layer.

11. (Currently Amended) The component of claim 8 wherein ~~said first film layer and said band of adhesive is disposed on the periphery of define lateral dimensions that are substantially equal such that said band of adhesive is substantially coextensive with said first film layer.~~

12. (Original) The component of claim 8 wherein said electrically conductive material is copper.

13. (Original) The component of claim 8 wherein another one of said first and second film layers is made of a material selected from the group consisting of aluminum, polytetrafluoroethylene, silicone, paper-based material, and cotton-based material.

14. (Withdrawn) A method of making printed circuit boards, said method comprising:

other of said conductive film layer and said non-functional film layer such that a portion of said one film layer extends beyond said other film layer;

assembling a book including a first steel plate, a first laminated component placed on said first steel plate, a core assembly placed on said first laminated component, a second laminated component placed on said core assembly, and a second steel plate placed on said second laminated component, wherein each laminated component is arranged so that its conductive film layer abuts said core assembly and its non-functional film layer abuts a corresponding one of said steel plates; and

subjecting said book to heat and pressure.

15. (Withdrawn) The method of claim 14 further comprising separating said non-functional film layers from said conductive film layers after subjecting said book to heat and pressure.

16. (Withdrawn) A method of making printed circuit boards, said method comprising:
providing laminated components, each laminated component comprising a first film layer, a second film layer disposed against said first film layer, and a band of adhesive joining said first and second film layers and defining a sealed central area inwardly thereof, said second film layer having larger lateral dimensions than said first film layer such that a portion of said second film layer extends beyond said first film layer, wherein one of said first and second film layers is made of an electrically conductive material;

assembling a book including a first steel plate, a first laminated component placed on said first steel plate, a core assembly placed on said first laminated component, a second laminated component placed on said core assembly, and a second steel plate placed on said second laminated component, wherein each laminated component is arranged so that its one film layer made of an electrically conductive materials abuts said core assembly; and

subjecting said book to heat and pressure.

17. (Withdrawn) The method of claim 16 further comprising separating said first and second film layers after subjecting said book to heat and pressure.

18. (New) A laminated component comprising:

a conductive film layer defining a first surface;

a non-functional film layer joined to the first surface of the conductive film layer; and

an adhesive disposed between the conductive film layer and the non-functional film layer, wherein the adhesion of the adhesive defines a central region and a flashing area opposite the central area on the conductive film layer, the flashing area suited for receiving flowing resin during the lamination process.

19. (New) The component of claim 18 wherein the conductive film layer is copper.

20. (New) The component of claim 18 wherein the non-functional film layer is made of a material selected from the group consisting of aluminum, polytetrafluoroethylene, silicone, paper-based material and cotton-based material.

21. (New) The component of claim 18 wherein the non-functional film layer is aluminum.

22. (New) The component of claim 18 wherein the non-functional film layer is polytetrafluoroethylene

23. (New) The component of claim 18 wherein the non-functional film layer is silicone.

24. (New) The component of claim 18 wherein the non-functional film layer is a paper-based material

25. (New) The component of claim 18 wherein the non-functional film layer is a cotton-based material

26. (New) The component of claim 18 wherein the adhesive is disposed between the conductive film layer and the non-functional film layer such that the adhesive is disposed at the periphery of the non-functional layer.

27. (New) The component of claim 18 wherein the conductive film layer is gold.

28. (New) The component of claim 18 wherein the conductive film layer is silver.

29. (New) The component of claim 18 wherein the conductive film layer is between 5 and 70 microns in thickness.

30. (New) The component of claim 18 wherein the non-functional film layer is between 12.7 and 76.2 microns in thickness.

Summary

In light of the above amendment, consideration of the subject patent application is respectfully requested. Any deficiency or overpayment should be charged or credited to Deposit Account No. 500282.

Respectfully submitted,



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